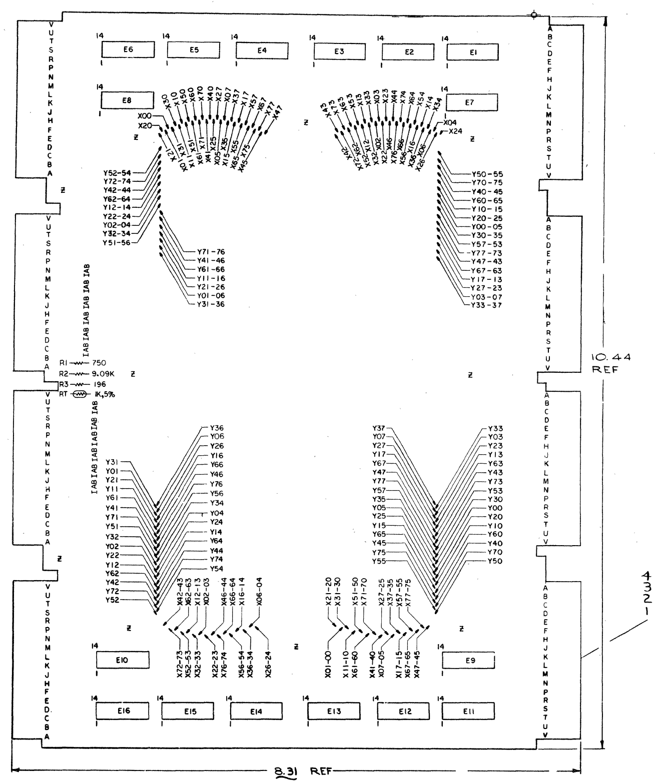
NOTES:

1. UNLESS OTHERWISE INDICATED:
   GND=AC2, AF1, AF2, AN1, AN2, AT1, AT2, BC1, BC2, BF1, BF2, BN1, BN2, BT1, BT2, CC1, CC2, CF1, CF2, CN1, CN2, CT1, CT2, DC1, DC2, DF1, DF2, DN1, DN2, DT1, DT2
2. DIODE ARRAYS WILL BE MOUNTED BY STACK VENDOR. DIODE ARRAYS ARE DEC25Ø1
3. THERMISTOR (RT) 1.ØK, 1% AT 25°C
4. 2501-01 MAY BE USED INTERCHANGEABLY WITH ITEM 9. PART# 1910010-01.



SEE NOTE 4

QTY.	REF DESIGNATION	DESCRIPTION	PART NO.	ITEM NO.
16	E1-E16	I.C. DEC 2501	1910010	9
1	RT	RES. 1K THERMISTOR 1%	1310071	8
1	R2	RES 9.09K 1/8W 1% MF	1304855	7
1	R3	RES. 196 1/8W 1% MF	1302956	6
1	R1	RES. 750 1/8W 1% MF	1302955	5
1		ETCHED CIRCUIT BOARD	5009057	4
REF		MODULE HISTORY LIST	B-MH G619-Ø-Ø	3
REF		ASSY/DRILLING HOLE LAYOUT	E-AH G619-Ø5	2
REF		X-Y COORDINATE HOLE LOC	K-CO-G619-Ø4	1

PARTS LIST

REV COLUMN

PRINTED CIRCUIT BOARD REVISION

CIRCUIT SCH REVISION

EQUIPMENT CORPORATION

PLANAR STACK BOARD G619

D-UA-H220-Ø-Ø

E CS G619-Ø-1

2/1

1 OF 2

IC TYPE | GND | +5V

GND AND 5V ARE USUALLY PIN 7 AND 14 RESPECTIVELY. EXCEPTIONS ARE STATED ABOVE

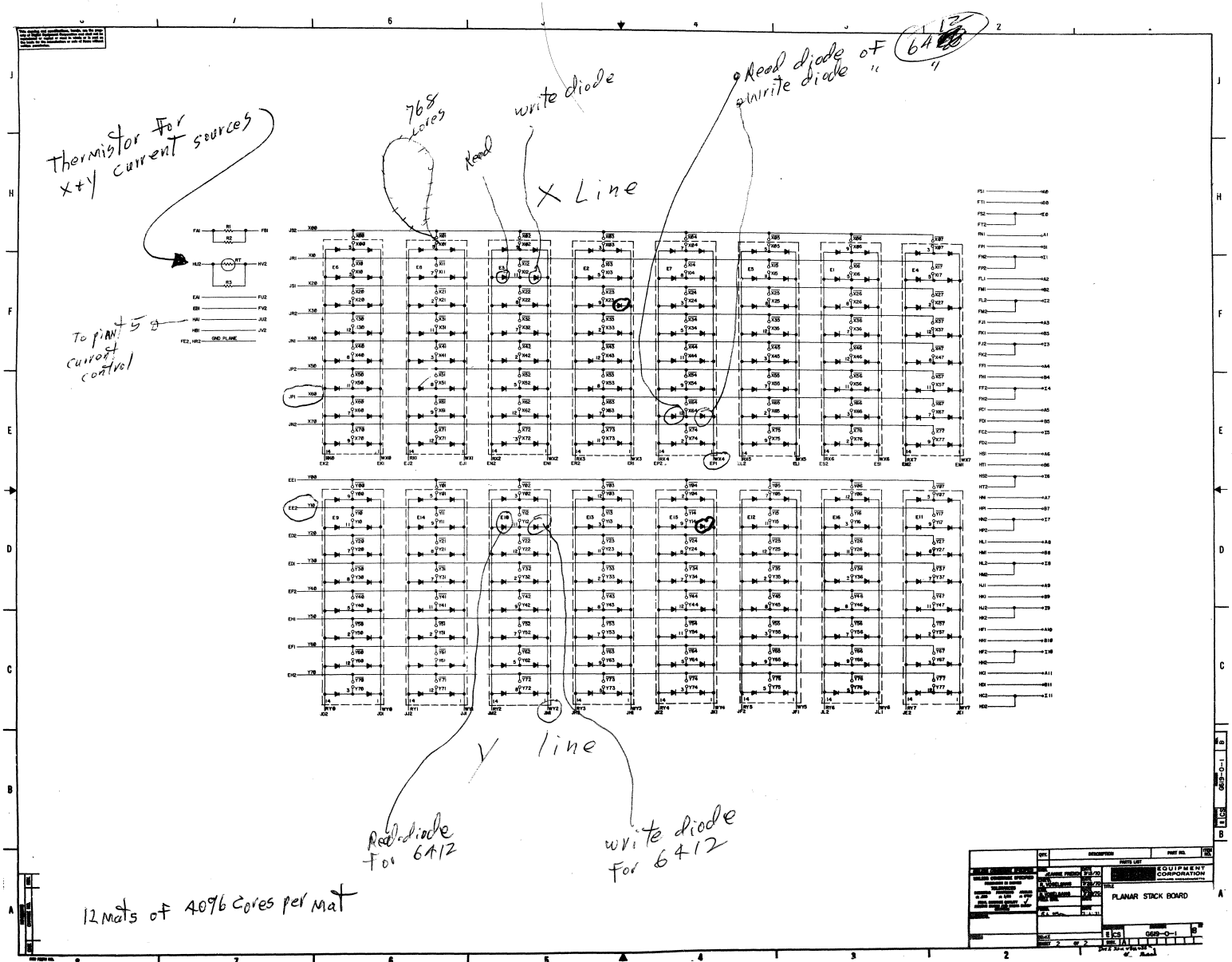
IC PIN LOCATIONS

ITEM NO	AWG	FROM PT	TO PT

JUMPER LIST

SEMICONDUCTOR CONVERSION CHART

CS G619-Ø-1


Thermistor for x+y current sources
768 cores
Read
write diode
X Line
Read diode of 6412
write diode " "
To pin 5 of current control
Y line
Read diode for 6412
write diode for 6412
12 mats of 4096 cores per mat
PLANAR STACK BOARD
EQUIPMENT CORPORATION
G619